ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC. Bannock	burn, Illinois, A	All rights reserved nations.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su	bstances w all lower	vithin the manufactu level materials for v	rer listed in the rest of the	item. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
IPC Web Site for Information on IPC-1752 Standard Form Ty				Form Type Distribute	*	⁴ Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material					ls and Mfg Information			
Supplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi								2025-05-04						
ontact Name Title - Contact					Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product Enviro Co			o Compliance		NA			Product-Env-Stewards@onsemi.com						
Authorized Representative* Title - Repres			esentative		Phone - Representative*			Email - Representative*						
Product-Env-Stewards P			Product Enviro Compliance			NA				Produe	Product-Env-Stewards@onsemi.com			
Requester Item Number	mber Mfr Item Numb		Number Mfr Item Name			Effective Date	Version	ersion Manufacturing Site			Weight*	UOM	Unit Type	
	ADT740 REEL	ADT7463ARQZ- REEL SYS MGMT CNT		TRLR IC		2025-05-04		Pł	PH1		143.27	mg	Each	
Aanufacturing Proccess Informa	tion													
Terminal Plating / Grid Array Ma	rray Material Terminal Base Alloy J-			J-STD-020 MSL	Rating	Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy			3		260		С	30	secoi	nds 3				
omments														
TTENTION: MSL 3 Rated item require	s Bake and I	Dry Pack (after	r electrical test)											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select	the Level (JIG A, JIG B	, Requester or Supplier) [B] select the substa	ance category (JIG or Requester) or enter	a value (Supplier). [C] selec	t the substance (JI	G) or enter the substa	nce and CAS (Other). [D]
select a RoHS exemption, if applie sigma range of distribution unless	cable [E] enter the weigh otherwise noted).	t of the substance or the P	PM concentration	[F] Optionally enter the positive (+) and	negative (-) tolerance in per-	cent (Note: percer	t tolerance values are	expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.85	mg	Supplier	Silicon (Si)	7440-21-3		4.85	mg
Die Attach	0.31	mg		Epoxy resin	proprietary data		0.0078	mg
			Supplier	Silver (Ag)	7440-22-4		0.248	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.0202	mg
			Supplier	Acrylic resins	Proprietary Data		0.0341	mg
Lead Frame	60.48	mg	Supplier	Zinc (Zn)	7440-66-6		0.0726	mg
			Supplier	Iron (Fe)	7439-89-6		1.4213	mg
			Supplier	Copper (Cu)	7440-50-8		58.968	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0181	mg
Lead Frame plating	0.6	mg	Supplier	Silver (Ag)	7440-22-4		0.6	mg
Mold Compound-Black	73.17	mg		Epoxy resin	proprietary data		3.6585	mg
			Supplier	Phenol Resin	Proprietary Data		2.9268	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		7.317	mg
			Supplier	Carbon Black (C)	1333-86-4		0.7317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		58.536	mg
Plating	3.23	mg	Supplier	Tin (Sn)	7440-31-5		3.23	mg
Wire Bond - Au	0.63	mg	Supplier	Gold (Au)	7440-57-5		0.63	mg